

# MA3SE02

Silicon epitaxial planar type

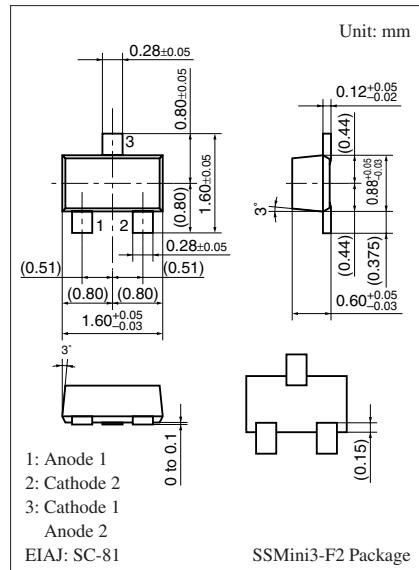
For cellular phone

## ■ Features

- High-frequency wave detection is possible
- Low forward voltage  $V_F$
- Small terminal capacitance  $C_t$

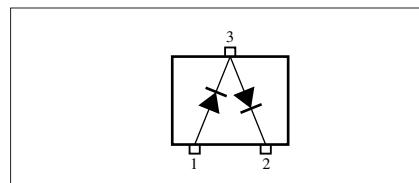
## ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	20	V
Maximum peak reverse voltage	$V_{RM}$	20	V
Forward current	$I_F$	35	mA
		25	
Peak forward current	$I_{FM}$	100	mA
		70	
Junction temperature	$T_j$	125	°C
Storage temperature	$T_{stg}$	-55 to +125	°C



Marking Symbol: M6B

Internal Connection



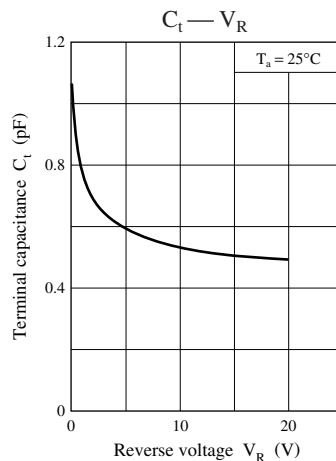
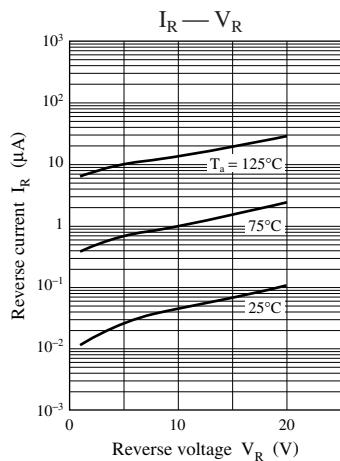
## ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_{F1}$	$I_F = 1 \text{ mA}$			0.40	V
	$V_{F2}$	$I_F = 35 \text{ mA}$			1.0	
Reverse current	$I_R$	$V_R = 15 \text{ V}$			200	nA
Terminal capacitance	$C_t$	$V_R = 0 \text{ V}, f = 1 \text{ MHz}$			1.2	pF
Forward dynamic resistance	$r_f$	$I_F = 5 \text{ mA}$		9		Ω

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. Absolute frequency of input and output is 2 GHz



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